	REVISIONS		
LTR	DESCRIPTION	DATE	APPROVED
В	Add vendor CAGE 18714 for device type 01. Remove one vendor; CAGE 31019.	11 DEC 86	mayfanck
С	Add device types 01FX and 012X for vendor CAGE 27014.	1 JULY 87	Mallande

AMSC N/A				Г	RE	, -			r						1	PAG	E	1		0	F	12				
26 December 1	984				SIZ		С			93		NO		٥	w G	N	ο.	84	10	9.						
Original date of drawing:					17		YE		Y	$()^{\prime}$						5	SPEE	D CI	MOS	TS, DUAL ILIC	. 4-	-CHA	NNE	L MU	I- ILTI	: -
Supply Center Dayton, Ohio					<u> </u>			- D	7	on en				al De	De epar	part tme	men nt o	ts a f De	nd / fense	Agen	cies	s of	the			
Defense Electro	nics			T				D В V		nst	Tal.	e.								Dable					10	3
OF PAGES	P	AGE	S	1	2	3	4	5	6	7	8	9	10	11	12	L	<u>L</u> .				<u> </u>					
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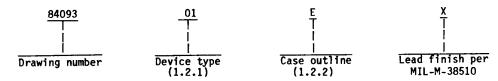
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DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

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- 1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".
 - 1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device type. The device type shall identify the circuit function as follows:

Device type Generic number Circuit function

O1 54HC153 Dual 4-channel multiplexer

1.2.2 <u>Case outlines</u>. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

 Outline letter
 Case outline

 E
 D-2 (16-lead, 1/4" x 7/8"), dual-in-line package

 F
 F-5 (16-lead, 1/4" x 3/8"), flat package

 2
 C-2 (20-terminal, .350" x .350"), square chip carrier package

1.3 Absolute maximum ratings.

```
-0.5 V dc to +7.0 V dc
Supply voltage range 1/------
                                                   -0.5 V dc to Vcc +0.5 V dc
-0.5 V dc to Vcc +0.5 V dc
DC input voltage- - - - - - - - - - - - -
DC output voltage - - - - - - - - - - - - -
Clamp diode current - - - - - - - - - - - -
                                                   ±20 mA
                                                   ±25 mA
DC output current (per pin) - - - - - - - -
±50_mA
                                                    -65°C to +150°C
                                                   500 mW 2/
Maximum power dissipation, (Pp) - - - - - - - Lead temperature (soldering, 10 seconds) - - - - Thermal resistance, junction-to-case (\theta_{JC}): 3/
                                                   +260°C
                                                   (See MIL-M-38510, appendix C) +60°C/W +175°C
  Cases E and F - - - - - - - - - - - -
  Junction temperature (Tj) - - - - - - - - -
```

- 1/ Unless otherwise specified, all voltages are referenced to ground.
- 2/ For $T_C = +100$ °C to +125°C, derate linearly at 12 mW/°C.
- $\frac{3}{}$ When a thermal resistance value is included in MIL-M-38510, appendix C, it shall superseded the value stated herein.

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Recommended operating conditions.

```
+2.0 V dc to +6.0 V dc -55°C to +125°C
Supply voltage range (V_{CC})- - - -
Case operating temperature range (T_C) - - - - -
Input rise or fall time: 4/
 0 to 1000 ns
0 to 500 ns
                                                   0 to 400 ns
```

2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510

Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883

Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

- 2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.
 - REQUIREMENTS
- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- $3.2\,$ Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
 - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
- 3.2.2 Truth table and logic diagram. The truth table and logic diagram shall be as specified on figure 2.
 - 3.2.3 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended case operating temperature range.
- 3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.

4/ See figure 3.

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	TABLE I	. Electrical performance	characteristi	cs.			
Test	Symbol		5°C cified <u>1</u> /	Group A subgroups 		Max	Unit
High-level output voltage	I V _{OH}	$ I_0 \le 20 \mu A$ $ V $	CC = 2.0 V CC = 4.5 V CC = 6.0 V CC = 4.5 V	1, 2, 3	1.9 4.4 5.9 3.7		٧
Low-level output voltage	i Vol I	$ I_0 \le 20 \mu A$ $ V_0 = 100 \text{J}_0 $	CC = 2.0 V CC = 4.5 V CC = 6.0 V CC = 4.5 V	1, 2, 3		0.1	V
High-level input voltage	 VIH	7!	/ _{CC} = 2.0 V / _{CC} = 4.5 V / _{CC} = 6.0 V	1, 2, 3	1.5 3.15		V V
Low-level input voltage	IV _{IL}		/ _{CC} = 2.0 V / _{CC} = 4.5 V / _{CC} = 6.0 V	1, 2, 3		0.3	V
Input capacitance	CIN	VIN = 0 V T _C = +25°C See 4.3.1c.		4	! !	10	pF
Quiescent current	Icc	ACC = 0.0 A AIN = ACC C	or GND	1, 2, 3		160	LμA
Input leakage current	IIIN	VCC = 6.0 V VIN = VCC	or GND	1, 2, 3	 	±1	 μ A
Functional tests		See 4.3.1d.		7	[

See footnotes at end of table.

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TABI	E I. Elec	ctrical performance ch	aracteristics - (Continued.			
Test	Symbol	Conditi -55°C < T _C < unless otherwise	ons _ +125°C - specified <u>1</u> /	Group A	Limits Min Max		Unit
	tpLH1 	T _C = +25°C C _L = 50 pF ±10% See figure 3	$V_{CC} = 2.0 \text{ V}$ $V_{CC} = 4.5 \text{ V}$ $V_{CC} = 6.0 \text{ V}$	9		29	ns
<u></u>	1	TC = -55°C +125°C C _L = 50 pF ±10% See figure 3	V _{CC} = 2.0 V V _{CC} = 4.5 V V _{CC} = 6.0 V	10, 11		220 44 38	ns
Propagation delay time, select to output	tpLH2	T _C = +25°C C _L = 50 pF ±10% See figure 3	V _{CC} = 2.0 V V _{CC} = 4.5 V V _{CC} = 6.0 V	9		195 39 33	ns
_	 	TC = -55°C +125°C C _L = 50 pF ±10% See figure 3	$V_{CC} = 2.0 \text{ V}$ $V_{CC} = 4.5 \text{ V}$ $V_{CC} = 6.0 \text{ V}$	10, 11		295 59 50	! ! ns ! !
Propagation delay time, loutput enable to output	torus	T _C = +25°C C _L = 50 pF ±10% See figure 3	V _{CC} = 2.0 V V _{CC} = 4.5 V V _{CC} = 6.0 V	9		110 22 19	ns
₹/		 TC = -55°C +125°C C _L = 50 pF ±10% See figure 3	V _{CC} = 2.0 V V _{CC} = 4.5 V V _{CC} = 6.0 V	10, 11		1 165 33 28	ns

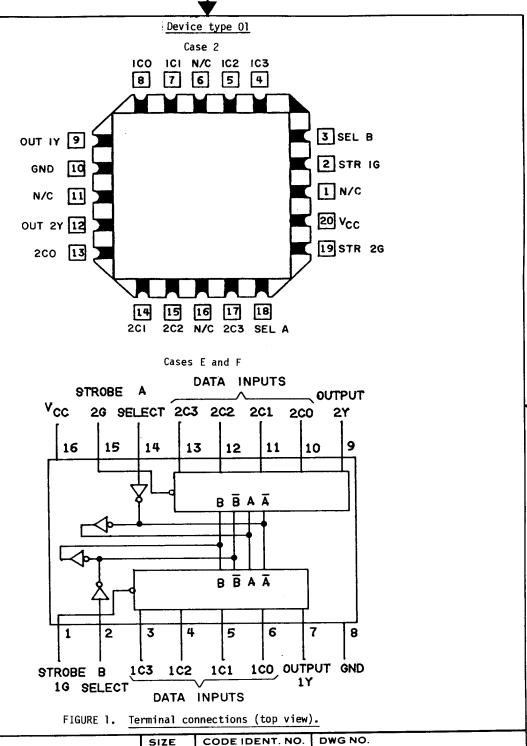
See footnotes at end of table.

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Test		Symbol	Condi	tions	Group A	Lii	mits	 Unit	
rest	1	Symbo i	1 -55°C < T _C		subgroups	Min	Max	1 ! !	
ransition time		tTHL tTLH	T _C = +25°C	V _{CC} = 2.0 V	9		 75 	l I ns	
	į	VIL.	C _L = 50 pF ±10%	$V_{CC} = 4.5 \text{ V}$	_i		15	1	
	!		See figure 3	$V_{CC} = 6.0 \text{ V}$			13	1	
	!		T _C = -55°C +125°C	V _{CC} = 2.0 V	10, 11	 	110	ns	
			C _L = 50 pF ±10%	$V_{CC} = 4.5 \text{ V}$	-		22	İ	
	! !		 See figure 3	$V_{CC} = 6.0 \text{ V}$	-		19		

- For a power supply of 5 V $\pm 10\%$ the worst case output voltages (V_{OH} and V_{OL}) occur for HC at 4.5 V. Thus, the 4.5 V values should be used when designing with this supply. Worst case V_{IH} and V_{IL}, occur at V_{CC} = 5.5 V and 4.5 V respectively. (The V_{IH} value at 5.5 V is 3.85 V.) The worst case leakage current (I_{IN}, I_{CC}, and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0 V values should be used. Power dissipation capacitance (Cp_D), typically 90 pF, determines the no load dynamic power consumption, P_D = Cp_D V_{CC} 2f+I_{CC} V_{CC}, and the no load dynamic current consumption, I_S = Cp_D V_{CC} f+I_{CC}.
- $\underline{2}/$ Test not required if applied as a forcing function for V_{OH} or V_{OL} .
- $\frac{3}{2}$ AC testing at $V_{CC} = 2.0$ V and $V_{CC} = 6.0$ V shall be guaranteed if not tested to the specified parameters.
- $\frac{4}{}$ Transition times, (t_{TLH}, t_{THL}), if not tested, shall be guaranteed to the specified parameters.
- 3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

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DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO

MILITARY DRAWING

SIZE CODE IDENT. NO. DWG NO. 84093

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Device type 01

Select Inputs		ata I			Strobe	Output
В А	CO	C1	C2	C3	G	Υ
X X L L L H L H H L H L H H	X L H X X X X	X X X H X X	X X X X L H X	X X X X X X L	X	

Select inputs A and B are common to both sections H = high level, L = low level, X = don't care

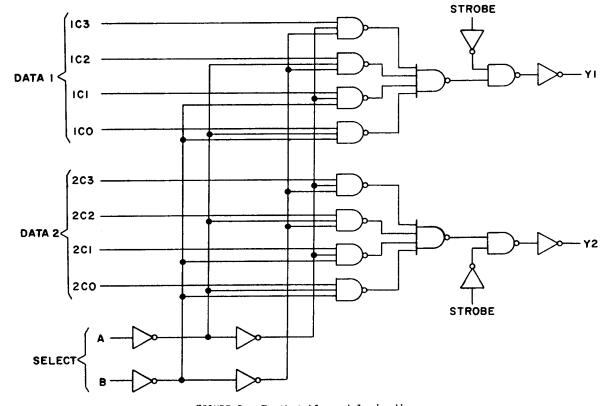
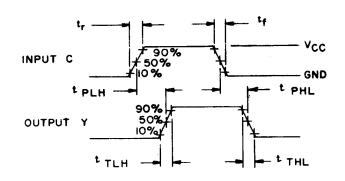
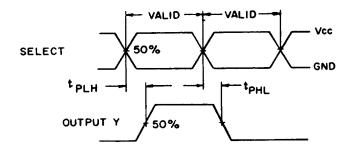


FIGURE 2. Truth table and logic diagram.

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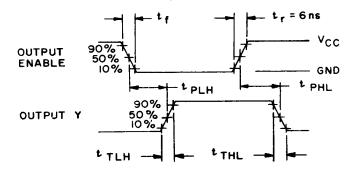


FIGURE 3. Switching waveform.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO SIZE CODE IDENT. NO. DWG NO. 84093 REV B PAGE 9

- 3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.8 <u>Verification and review.</u> DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test (method 1015 of MIL-STD-883).
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125$ °C, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 <u>Ouality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 5, 6, and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - c. Subgroup 4 ($C_{
 m IN}$ measurement) shall be measured only for the initial test and after process or design changes which may affect input capacitance.
 - d. Subgroup 7 tests sufficiently to verify the truth table.
 - 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*, 2, 9
Group A test requirements (method 5005)	1, 2, 3, 4, 7, 9, 10, 11**
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3
Additional electrical subgroups for group C periodic inspections	

PDA applies to subgroup 1. Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.

PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
 - 6.2 Replaceability. Replaceability is determined as follows:
 - a. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
 - b. When a QPL source is established, the part numbered device specified in this drawing will be replaced by the microcircuit identified as part number M38510/66202B--.
- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

CODE IDENT. NO. SIZE DWG NO. MILITARY DRAWING 14933 Α 84093 **DEFENSE ELECTRONICS SUPPLY CENTER** DAYTON, OHIO REV PAGE 11 В

6.4 Approved sources of supply. Approved sources of supply are listed herein. Additional sources will be added as they become available. The vendors listed herein have agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing part number	Vendor CAGE number	Vendor similar part number <u>1</u> /	Replacement military specification part number
8409301EX	01295	SNJ54HC153J	M38510/66202BEX
8409301EX	04713	54HC153/BEAJC	M38510/66202BEX
8409301EX	18714	 CD54HC153F/3A	M38510/66202BEX
8409301EX	27014	 MM54HC153J/883B	M38510/66202BEX
8409301FX	27014	 MM54HC153W/883	M38510/66202BFX
8409301FX	01295	SNJ54HC153W	M38510/66202BFX
8409 3 012X	27014	MM54HC153E/883	M38510/66202B2X
84093012X	01295	SNJ54HC153FK	M38510/66202B2X
84093012X	04713	 54HC153M/B2CJC	M38510/66202B2X

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number	Vendor name and address		
01295	Texas Instruments, Inc. P.O Box 6448 Midland, TX 79701		
27014	National Semiconductor P.O. Box 58090 Santa Clara, CA 95052-8090		
04713	Motorola, Inc. 7402 S. Price Road Tempe, AZ 85283		
18714	RCA Corporation Solid State Division Route 202 Somerville, NJ 08876		

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